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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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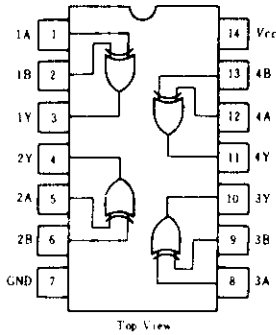
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HD74LS386

●Quadruple 2-input Exclusive-OR Gates

PIN ARRANGEMENT



FUNCTION TABLE

Inputs		Output
A	B	
L	L	L
L	H	H
H	L	H
H	H	L

H: high level, L: low level.

ELECTRICAL CHARACTERISTICS ($T_a = -20 \sim +75^\circ\text{C}$)

Item	Symbol	Test Conditions	min	typ*	max	Unit
Input voltage	V_{IH}		2.0	—	—	V
	V_{IL}		—	—	0.8	V
Output voltage	V_{OH}	$V_{CC} = 4.75\text{V}$, $V_{IH} = 2\text{V}$, $V_{IL} = 0.8\text{V}$, $I_{OH} = -400\mu\text{A}$	2.7	—	—	V
	V_{OL}	$V_{CC} = 4.75\text{V}$, $V_{IH} = 2\text{V}$, $V_{IL} = 0.8\text{V}$	—	—	0.4	V
			—	—	0.5	
Input current	I_{IH}	$V_{CC} = 5.25\text{V}$, $V_I = 2.7\text{V}$	—	—	40	μA
	I_{IL}	$V_{CC} = 5.25\text{V}$, $V_I = 0.4\text{V}$	—	—	-0.8	mA
	I_I	$V_{CC} = 5.25\text{V}$, $V_I = 7\text{V}$	—	—	0.2	mA
Short-circuit output current	I_{OS}	$V_{CC} = 5.25\text{V}$	-20	—	100	mA
Supply current**	I_{CC}	$V_{CC} = 5.25\text{V}$	—	6.1	10	mA
Input clamp voltage	V_{IK}	$V_{CC} = 4.75\text{V}$, $I_{IK} = -18\text{mA}$	—	—	-1.5	V

* $V_{CC} = 5\text{V}$, $T_a = 25^\circ\text{C}$

** I_{CC} is measured with all outputs open and all inputs grounded.

SWITCHING CHARACTERISTICS ($V_{CC} = 5\text{V}$, $T_a = 25^\circ\text{C}$)

Item	Symbol	Inputs	Test Conditions		min	typ	max	Unit
Propagation delay time	t_{PLH}	A or B	Other inputs "L"	$C_L = 15\text{pF}$, $R_L = 2\text{k}\Omega$	—	12	23	ns
	t_{PHL}				—	10	17	
	t_{PLH}	A or B	Other inputs "H"		—	20	30	ns
	t_{PHL}				—	13	22	

Note) Refer to Test Circuit and Waveform of the Common Item

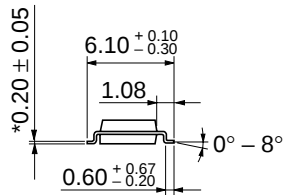


Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.23 g



Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

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